

App. Serial No. 10/518,736  
Docket No.: NL020528US

**In the Claims:**

Please amend claims 1-5 and 10-11 as indicated below. This listing of claims replaces all prior versions.

1. (*Currently Amended*) Method for manufacturing on a substrate a semiconductor device with a floating-gate and a control-gate, comprising the steps of:
  - first forming isolation zones in the substrate,
  - thereafter forming a floating gate on the substrate between two of the isolation zones,
  - thereafter extending the floating gate using conductive spacers, and
  - thereafter forming a control gate over the floating gate and the conductive spacers.
2. (*Currently Amended*) Method according to claim 1, wherein the step of forming the floating gate comprises:
  - providing the floating gate on the substrate, the floating gate having two opposite walls located above the isolation zones, and
  - forming [[a]] recesses in the isolation zones under the opposite walls of the floating gate.
3. (*Currently Amended*) Method according to claim 2, wherein the step of providing the floating gate, comprises:
  - depositing a floating gate layer, and
  - forming slits in the floating gate layer, thus forming the opposite walls of the floating gate.
4. (*Currently Amended*) Method according to claim 2, wherein the step of extending the floating gate comprises depositing a conductive layer on the opposite walls of the floating gate and on the walls of the recesses in the isolation zones.

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5. (*Currently Amended*) Method according to claim 4, wherein the step of depositing a conductive layer on the opposite walls of the floating gate and on the walls of the recesses in the isolation zones comprises:

depositing a conductive layer over the floating gate and in the recesses in the isolation zones, and  
etching the conductive layer.

6. (*Original*) Method according to claim 1, further comprising a step of forming a dielectric layer on the floating gate and on the conductive spacers before forming the control gate.

7. (*Original*) Method according to claim 1, wherein the isolation zones are shallow trench isolation (STI) zones.

8. (*Original*) Method according to claim 1, wherein the isolation zones are LOCOS regions.

9. (*Original*) Method according to claim 2, wherein a recess in an isolation zone is formed by etching.

10. (*Currently Amended*) Method according to claim 1, further comprising the a step of providing a tunnel oxide between the semiconductor substrate and the floating gate.

11. (*Currently Amended*) Method according to claim 1, wherein the step of forming the control gate comprises:

depositing a control gate layer, and  
patterning the control gate layer to form the control gate.

12. (*Original*) Method according to claim 1, wherein the conductive spacers are polysilicon spacers.

Claims 13-18 (*Cancelled*)